

WHAT IS CLAIMED IS:

1. A test vehicle ball grid array package comprising:
a PCB having bonding fingers;
5 an adhesive material being coated on an edge of the PCB;
a sealing post being adhered on the adhesive material;
a semiconductor testing chip having a plurality of
bonding pads adhered on the PCB;
a plurality of metal wires separately connecting bonding
10 pads of the PCB to the bonding fingers of the PCB;
a sealing cap adhered on a sealing post for sealing the
semiconductor chip; and

15 a plurality of solder balls adhered to a lower side of
the PCB.

2. A test vehicle ball grid array package according to
claim 1, wherein each of the sealing post and the sealing cap
is made from non-conductive material.

20 3. A test vehicle ball grid array package according to
claim 1, wherein an extrusion is formed at a upper end of the
sealing post.

4. A test vehicle ball grid array package according to

claim 1, wherein the sealing cap is adhered on the extrusion of the sealing post.

5 5. A test vehicle ball grid array package according to claim 4, wherein the sealing cap is adhered on the extrusion of the sealing post by a low temperature thermoplastic tape or a material similar to low temperature thermoplastic tape.

10 6. A test vehicle ball grid array package according to claim 1, wherein the semiconductor chip is a center pad-type chip or an edge pad-type chip.